

BYW32GP THRU BYW36GP

SINTERED GLASS JUNCTION
FAST SWITCHING PLASTIC RECTIFIER
VOLTAGE:200 TO 600V CURRENT: 2.0A



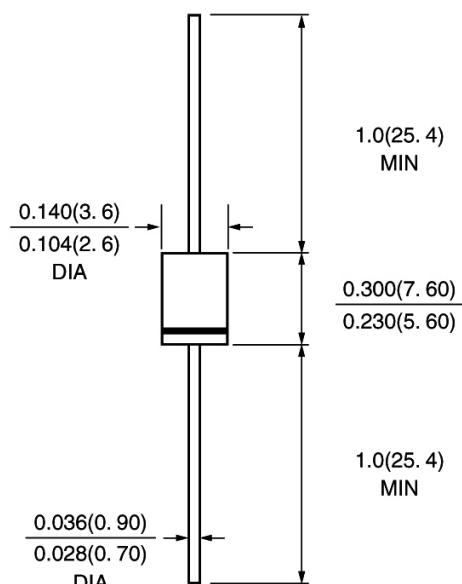
FEATURE

High temperature metallurgically bonded construction
Sintered glass cavity free junction
Capability of meeting environmental standard of
MIL-S-19500
High temperature soldering guaranteed
350°C /10sec/0.375"lead length at 5 lbs tension
Operate at Ta =55°C with no thermal run away
Typical Ir<0.1μA

MECHANICAL DATA

Terminal: Plated axial leads solderable per
MIL-STD 202E, method 208C
Case: Molded with UL-94 Class V-0 recognized Flame
Retardant Epoxy
Polarity: color band denotes cathode
Mounting position: any

DO-15\DO-204AC



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half-wave, 60HZ, resistive or inductive load rating at 25°C, unless otherwise stated)

	SYMBOL	BYW 32GP	BYW 33GP	BYW 34GP	BYW 35GP	BYW 36GP	units
Maximum Recurrent Peak Reverse Voltage	Vrrm	200	300	400	500	600	V
Maximum RMS Voltage	Vrms	140	210	280	350	420	V
Maximum DC blocking Voltage	Vdc	200	300	400	500	600	V
Maximum Average Forward Rectified Current 3/8"lead length at Ta =45°C	If(av)			2.0			A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	Ifsm			50			A
Maximum Forward Voltage at rated Forward Current and 25°C at 1.0A	Vf			1.1			V
Non-repetitive peak reverse avalanche energy (Note 1)	Ersm			10			mJ
Maximum DC Reverse Current Ta =25°C at rated DC blocking voltage Ta =125°C	Ir			5.0			μA
Maximum Reverse Recovery Time (Note 2)	Trr			150			μA
Typical Junction Capacitance (Note 3)	Cj			200			nS
Typical Thermal Resistance (Note 4)	R(ja)			60			pF
Storage and Operating Junction Temperature	Tstg, Tj			20			°C/W
				-65 to +175			°C

Note: 1.R=400mA; Tj=Tjmax prior to surge; inductive load switched off

2.Reverse Recovery Condition If =0.5A, Ir =1.0A, Irr =0.25A

3.Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc

4.Thermal Resistance from Junction to Ambient at 3/8"lead length, P.C. Board Mounted

RATINGS AND CHARACTERISTIC CURVES BYW32GP THRU BYW36GP

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Figure 1. Max. Thermal Resistance vs. Lead Length

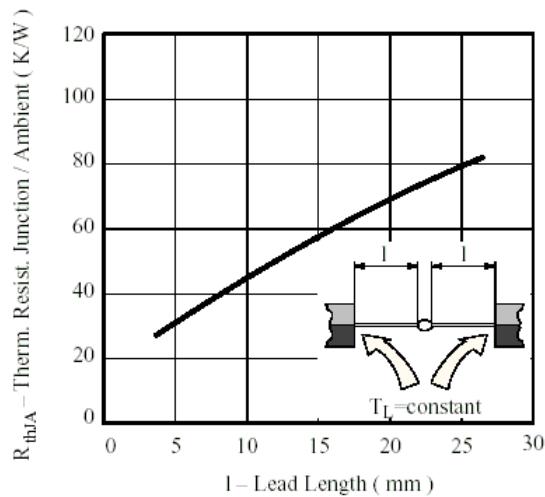


Figure 2. Reverse Current vs. Junction Temperature

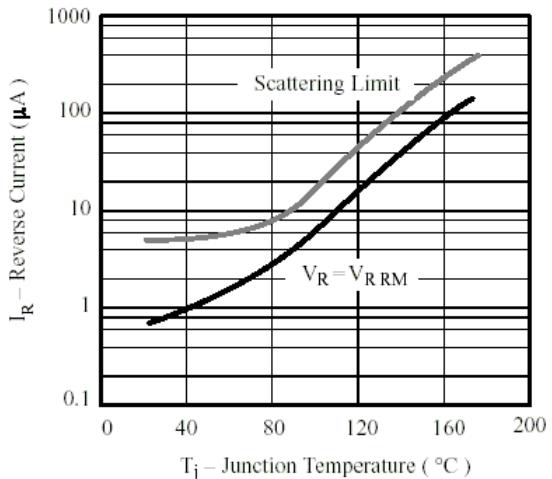


Figure 3. Max. Average Forward Current vs. Ambient Temperature

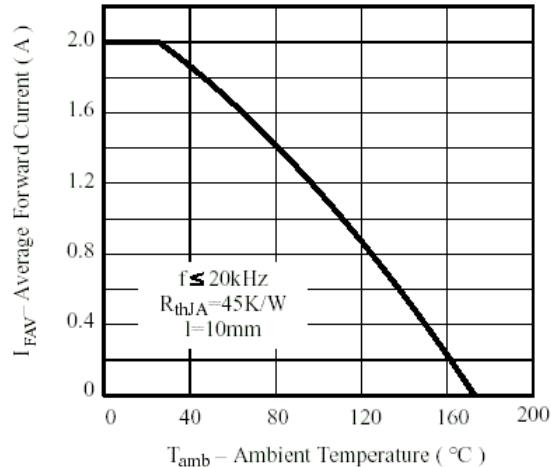


Figure 4. Max. Forward Current vs. Forward Voltage

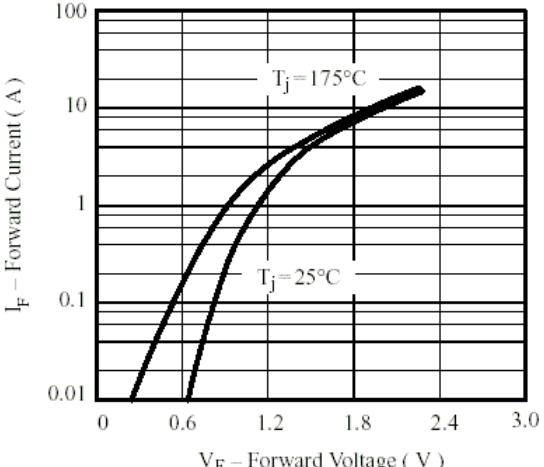


Figure 5. Typ. Diode Capacitance vs. Reverse Voltage

